

WHAT IS CLAIMED IS:

1. A wiring board to which a semiconductor chip is to be bonded while directing a surface of the semiconductor chip toward the wiring board, the wiring board comprising:
 - 5 a connection electrode formed on a bonding surface to which the semiconductor chip is to be bonded, the connection electrode being for a connection with the semiconductor chip;
 - an insulating film formed on the bonding surface, the insulating film having an opening to expose the connection 10 electrode; and
 - a low-melting-point metallic part provided on the connection electrode in the opening, the low-melting-point metallic part being made of a low-melting-point metallic material whose solidus temperature is lower than that of the connection 15 electrode.
2. A wiring board according to Claim 1, wherein a volume of an inside of the opening is greater than a sum of a volume of a connection electrode and a volume of the low-melting-point metallic part.
- 20 3. A semiconductor device comprising:
 - a wiring board; and
 - a semiconductor chip having a projection electrode formed on a surface on which a functional element is formed, the projection electrode being electrically connected to the 25 functional element, the semiconductor chip being bonded to a

bonding surface of the wiring board with the surface of the semiconductor chip facing the bonding surface;

the wiring board including:

a connection electrode formed on the bonding surface,

5 the connection electrode being used to make a connection with the semiconductor chip;

an insulating film formed on the bonding surface, the insulating film having an opening to expose the connection electrode; and

10 a low-melting-point metallic part provided on the connection electrode in the opening, the low-melting-point metallic part being made of a low-melting-point metallic material whose solidus temperature is lower than that of the connection electrode.